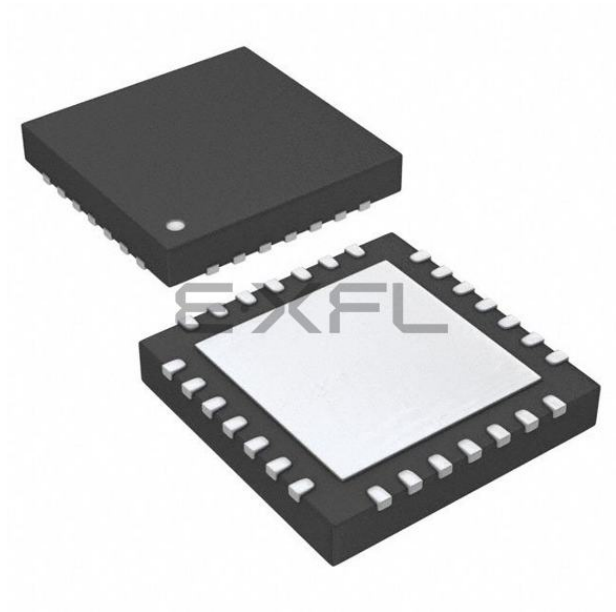

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## What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

## Applications of "Embedded - Microcontrollers"

| Details | |
|---|---|
| Product Status | Active |
| Core Processor | PIC |
| Core Size | 8-Bit |
| Speed | 40MHz |
| Connectivity | CANbus, I²C, SPI, UART/USART |
| Peripherals | Brown-out Detect/Reset, HLVD, POR, PWM, WDT |
| Number of I/O | 25 |
| Program Memory Size | 16KB (8K x 16) |
| Program Memory Type | FLASH |
| EEPROM Size | 256 x 8 |
| RAM Size | 768 x 8 |
| Voltage - Supply (Vcc/Vdd) | 4.2V ~ 5.5V |
| Data Converters | A/D 8x10b |
| Oscillator Type | Internal |
| Operating Temperature | -40°C ~ 85°C (TA) |
| Mounting Type | Surface Mount |
| Package / Case | 28-VQFN Exposed Pad |
| Supplier Device Package | 28-QFN (6x6) |
| Purchase URL | https://www.e-xfl.com/product-detail/microchip-technology/pic18f2480t-i-ml |

## 2.2 Power Supply Pins

### 2.2.1 DECOUPLING CAPACITORS

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS, is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A 0.1 μF (100 nF), 10-20V capacitor is recommended. The capacitor should be a low-ESR device, with a resonance frequency in the range of 200 MHz and higher. Ceramic capacitors are recommended.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is no greater than 0.25 inch (6 mm).
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise (upward of tens of MHz), add a second ceramic type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 μF to 0.001 μF. Place this second capacitor next to each primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible (e.g., 0.1 μF in parallel with 0.001 μF).
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB trace inductance.

### 2.2.2 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits, including microcontrollers, to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 μF to 47 μF.

### 2.2.3 CONSIDERATIONS WHEN USING BOR

When the Brown-out Reset (BOR) feature is enabled, a sudden change in VDD may result in a spontaneous BOR event. This can happen when the microcontroller is operating under normal operating conditions, regardless of what the BOR set point has been programmed to, and even if VDD does not approach the set point. The precipitating factor in these BOR events is a rise or fall in VDD with a slew rate faster than 0.15V/μs.

An application that incorporates adequate decoupling between the power supplies will not experience such rapid voltage changes. Additionally, the use of an electrolytic tank capacitor across VDD and VSS, as described above, will be helpful in preventing high slew rate transitions.

If the application has components that turn on or off, and share the same VDD circuit as the microcontroller, the BOR can be disabled in software by using the SBOREN bit before switching the component. Afterwards, allow a small delay before re-enabling the BOR. By doing this, it is ensured that the BOR is disabled during the interval that might cause high slew rate changes of VDD.

| | |
|---|---|
| **Note:** | Not all devices incorporate software BOR control. See **Section 5.0 "Reset"** for device-specific information. |

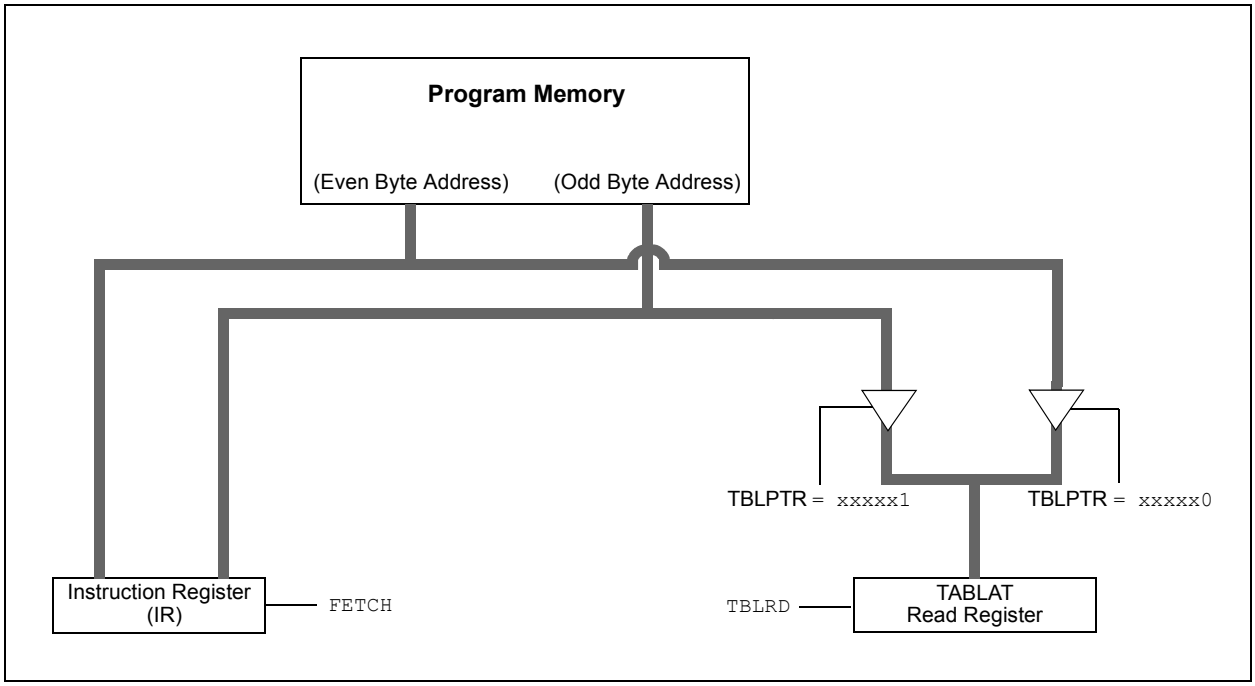
## 7.3 Reading the Flash Program Memory

The TBLRD instruction is used to retrieve data from program memory and place it into data RAM. Table reads from program memory are performed one byte at a time.

TBLPTR points to a byte address in program space. Executing TBLRD places the byte pointed to into TABLAT. In addition, TBLPTR can be modified automatically for the next table read operation.

The internal program memory is typically organized by words. The Least Significant bit of the address selects between the high and low bytes of the word. Figure 7-4 shows the interface between the internal program memory and the TABLAT.

**FIGURE 7-4: READS FROM FLASH PROGRAM MEMORY**




**EXAMPLE 7-1: READING A FLASH PROGRAM MEMORY WORD**

```
            MOVLW     CODE_ADDR_UPPER           ; Load TBLPTR with the base
            MOVWF     TBLPTRU                   ; address of the word
            MOVLW     CODE_ADDR_HIGH
            MOVWF     TBLPTRH
            MOVLW     CODE_ADDR_LOW
            MOVWF     TBLPTRL
READ_WORD
            TBLRD*+                             ; read into TABLAT and increment
            MOVF      TABLAT, W                 ; get data
            MOVWF     WORD_EVEN
            TBLRD*+                             ; read into TABLAT and increment
            MOVF      TABLAT, W                 ; get data
            MOVF      WORD_ODD
```

## 11.4 PORTD, TRISD and LATD Registers

| **Note:** | PORTD is only available on PIC18F4X80 devices. |
|---|---|

PORTD is an 8-bit wide, bidirectional port. The corresponding Data Direction register is TRISD. Setting a TRISD bit (= 1) will make the corresponding PORTD pin an input (i.e., put the corresponding output driver in a high-impedance mode). Clearing a TRISD bit (= 0) will make the corresponding PORTD pin an output (i.e., put the contents of the output latch on the selected pin).

The Output Latch register (LATD) is also memory mapped. Read-modify-write operations on the LATD register read and write the latched output value for PORTD.

All pins on PORTD are implemented with Schmitt Trigger input buffers. Each pin is individually configurable as an input or output.

Four of the PORTD pins are multiplexed with outputs P1A, P1B, P1C and P1D of the Enhanced CCP module. The operation of these additional PWM output pins is covered in greater detail in **Section 17.0 "Enhanced Capture/Compare/PWM (ECCP) Module"**.

Four of the PORTD pins are multiplexed with the input pins of the comparators. The operation of these input pins is covered in greater detail in **Section 21.0 "Comparator Module"**.

| **Note:** | On a Power-on Reset, these pins are configured as analog inputs. |
|---|---|

PORTD can also be configured as an 8-bit wide microprocessor port (Parallel Slave Port) by setting control bit, PSPMODE (TRISE<4>). In this mode, the input buffers are TTL. See **Section 11.6 "Parallel Slave Port"** for additional information on the Parallel Slave Port (PSP).

**EXAMPLE 11-4: INITIALIZING PORTD**

```
CLRF    PORTD   ; Initialize PORTD by
                ; clearing output
                ; data latches
CLRF    LATD    ; Alternate method
                ; to clear output
                ; data latches
MOVLW   0CFh    ; Value used to
                ; initialize data
                ; direction
MOVWF   TRISD   ; Set RD<3:0> as inputs
                ; RD<5:4> as outputs
                ; RD<7:6> as inputs
```

#### 18.4.3.2 Reception

When the R/$\overline{W}$ bit of the address byte is clear and an address match occurs, the R/$\overline{W}$ bit of the SSPSTAT register is cleared. The received address is loaded into the SSPBUF register and the SDA line is held low ($\overline{ACK}$).

When the address byte overflow condition exists, then the no Acknowledge ($\overline{ACK}$) pulse is given. An overflow condition is defined as either bit, BF (SSPSTAT<0>), is set, or bit, SSPOV (SSPCON1<6>), is set.

An MSSP interrupt is generated for each data transfer byte. Flag bit, SSPIF (PIR1<3>), must be cleared in software. The SSPSTAT register is used to determine the status of the byte.

If SEN is enabled (SSPCON2<0> = 1), RC3/SCK/SCL will be held low (clock stretch) following each data transfer. The clock must be released by setting bit, CKP (SSPCON<4>). See **Section 18.4.4 "Clock Stretching"** for more details.

#### 18.4.3.3 Transmission

When the R/$\overline{W}$ bit of the incoming address byte is set and an address match occurs, the R/$\overline{W}$ bit of the SSPSTAT register is set. The received address is loaded into the SSPBUF register. The $\overline{ACK}$ pulse will be sent on the ninth bit and pin RC3/SCK/SCL is held low regardless of SEN (see **Section 18.4.4 "Clock Stretching"** for more details). By stretching the clock, the master will be unable to assert another clock pulse until the slave is done preparing the transmit data. The transmit data must be loaded into the SSPBUF register which also loads the SSPSR register. Then, the RC3/SCK/SCL pin should be enabled by setting bit, CKP (SSPCON1<4>). The eight data bits are shifted out on the falling edge of the SCL input. This ensures that the SDA signal is valid during the SCL high time (Figure 18-9).

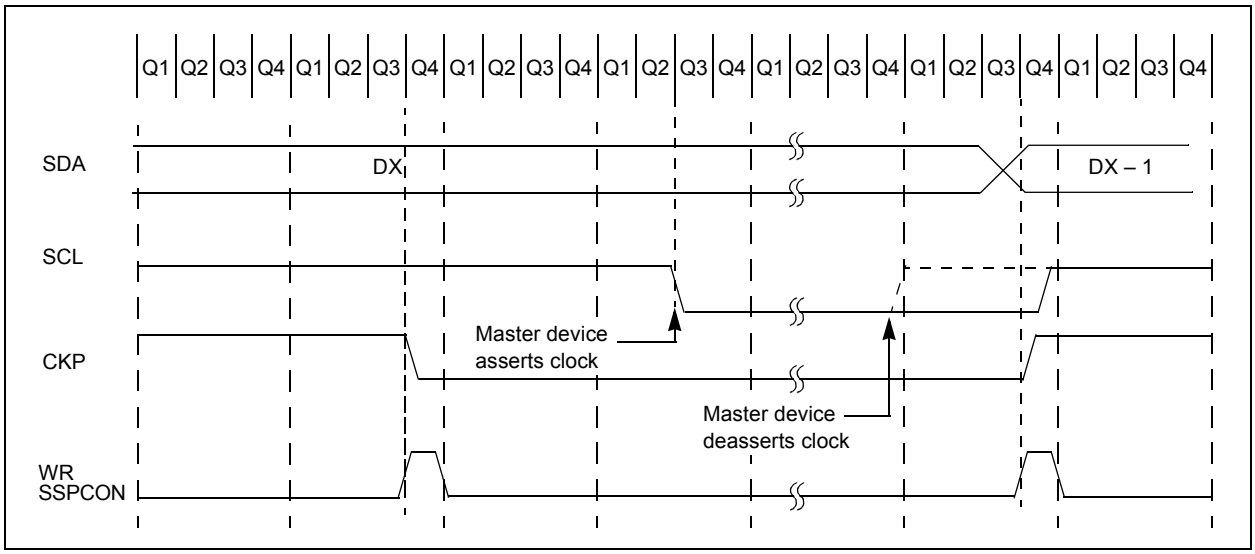
The $\overline{ACK}$ pulse from the master-receiver is latched on the rising edge of the ninth SCL input pulse. If the SDA line is high (not $\overline{ACK}$), then the data transfer is complete. In this case, when the $\overline{ACK}$ is latched by the slave, the slave logic is reset and the slave monitors for another occurrence of the Start bit. If the SDA line was low ($\overline{ACK}$), the next transmit data must be loaded into the SSPBUF register. Again, pin, RC3/SCK/SCL, must be enabled by setting bit, CKP.

An MSSP interrupt is generated for each data transfer byte. The SSPIF bit must be cleared in software and the SSPSTAT register is used to determine the status of the byte. The SSPIF bit is set on the falling edge of the ninth clock pulse.

#### 18.4.4.5 Clock Synchronization and the CKP bit

When the CKP bit is cleared, the SCL output is forced to '0'. However, setting the CKP bit will not assert the SCL output low until the SCL output is already sampled low. Therefore, the CKP bit will not assert the SCL line until an external $I^2C$ master device has already asserted the SCL line. The SCL output will remain low until the CKP bit is set and all other devices on the $I^2C$ bus have deasserted SCL. This ensures that a write to the CKP bit will not violate the minimum high time requirement for SCL (see Figure 18-12).

**FIGURE 18-12: CLOCK SYNCHRONIZATION TIMING**



#### 18.4.6.1 I²C Master Mode Operation

The master device generates all of the serial clock pulses and the Start and Stop conditions. A transfer is ended with a Stop condition or with a Repeated Start condition. Since the Repeated Start condition is also the beginning of the next serial transfer, the I²C bus will not be released.

In Master Transmitter mode, serial data is output through SDA while SCL outputs the serial clock. The first byte transmitted contains the slave address of the receiving device (7 bits) and the Read/Write (R/$\overline{W}$) bit. In this case, the R/$\overline{W}$ bit will be logic '0'. Serial data is transmitted 8 bits at a time. After each byte is transmitted, an Acknowledge bit is received. Start and Stop conditions are output to indicate the beginning and the end of a serial transfer.

In Master Receive mode, the first byte transmitted contains the slave address of the transmitting device (7 bits) and the R/$\overline{W}$ bit. In this case, the R/$\overline{W}$ bit will be logic '1' Thus, the first byte transmitted is a 7-bit slave address followed by a '1' to indicate the receive bit. Serial data is received via SDA, while SCL outputs the serial clock. Serial data is received 8 bits at a time. After each byte is received, an Acknowledge bit is transmitted. Start and Stop conditions indicate the beginning and end of transmission.

The Baud Rate Generator used for the SPI mode operation is used to set the SCL clock frequency for either 100 kHz, 400 kHz or 1 MHz I²C operation. See **Section 18.4.7 "Baud Rate"** for more details.

A typical transmit sequence would go as follows:

1. The user generates a Start condition by setting the Start Enable bit, SEN (SSPCON2<0>).
2. SSPIF is set. The MSSP module will wait the required start time before any other operation takes place.
3. The user loads the SSPBUF with the slave address to transmit.
4. Address is shifted out the SDA pin until all 8 bits are transmitted.
5. The MSSP module shifts in the ACK bit from the slave device and writes its value into the SSPCON2 register (SSPCON2<6>).
6. The MSSP module generates an interrupt at the end of the ninth clock cycle by setting the SSPIF bit.
7. The user loads the SSPBUF with eight bits of data.
8. Data is shifted out the SDA pin until all 8 bits are transmitted.
9. The MSSP module shifts in the ACK bit from the slave device and writes its value into the SSPCON2 register (SSPCON2<6>).
10. The MSSP module generates an interrupt at the end of the ninth clock cycle by setting the SSPIF bit.
11. The user generates a Stop condition by setting the Stop Enable bit, PEN (SSPCON2<2>).
12. Interrupt is generated once the Stop condition is complete.

### 18.4.7 BAUD RATE

In $I^2C$ Master mode, the Baud Rate Generator (BRG) reload value is placed in the lower 7 bits of the SSPADD register (Figure 18-17). When a write occurs to SSPBUF, the Baud Rate Generator will automatically begin counting. The BRG counts down and stops until another reload has taken place. The BRG count is decremented twice per instruction cycle (TCY) on the Q2 and Q4 clocks. In $I^2C$ Master mode, the BRG is reloaded automatically.

Once the given operation is complete (i.e., transmission of the last data bit is followed by ACK), the internal clock will automatically stop counting and the SCL pin will remain in its last state.

Table 18-3 demonstrates clock rates based on instruction cycles and the BRG value loaded into SSPADD.

**FIGURE 18-17: BAUD RATE GENERATOR BLOCK DIAGRAM**

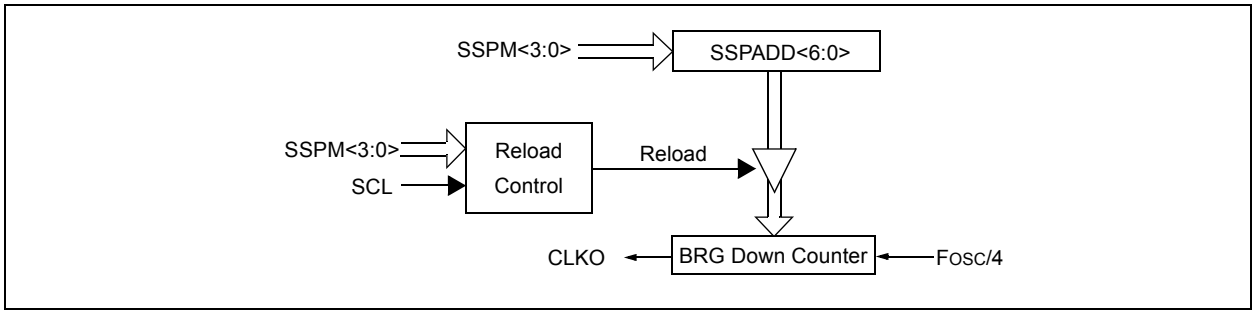



**TABLE 18-3: $I^2C$™ CLOCK RATE W/BRG**

| FCY | FCY*2 | BRG Value | FSCL (2 Rollovers of BRG) |
|---|---|---|---|
| 10 MHz | 20 MHz | 19h | 400 kHz |
| 10 MHz | 20 MHz | 20h | 312.5 kHz |
| 10 MHz | 20 MHz | 64h | 100 kHz |
| 4 MHz | 8 MHz | 0Ah | 400 kHz |
| 4 MHz | 8 MHz | 0Dh | 308 kHz |
| 4 MHz | 8 MHz | 28h | 100 kHz |
| 1 MHz | 2 MHz | 03h | 333 kHz |
| 1 MHz | 2 MHz | 0Ah | 100 kHz |

**REGISTER 19-3: BAUDCON: BAUD RATE CONTROL REGISTER**

| R/W-0 | R-1 | U-0 | R/W-0 | R/W-0 | U-0 | R/W-0 | R/W-0 |
|---|---|---|---|---|---|---|---|
| ABDOVF | RCIDL | — | SCKP | BRG16 | — | WUE | ABDEN |
| bit 7 | | | | | | | bit 0 |

| **Legend:** | | | |
|---|---|---|---|
| R = Readable bit | W = Writable bit | U = Unimplemented bit, read as '0' | |
| -n = Value at POR | '1' = Bit is set | '0' = Bit is cleared | x = Bit is unknown |

bit 7 **ABDOVF**: Auto-Baud Acquisition Rollover Status bit
1 = A BRG rollover has occurred during Auto-Baud Rate Detect mode (must be cleared in software)
0 = No BRG rollover has occurred

bit 6 **RCIDL**: Receive Operation Idle Status bit
1 = Receive operation is Idle
0 = Receive operation is active

bit 5 **Unimplemented:** Read as '0'

bit 4 **SCKP**: Synchronous Clock Polarity Select bit
Asynchronous mode:
Unused in this mode.
Synchronous mode:
1 = Idle state for clock (CK) is a high level
0 = Idle state for clock (CK) is a low level

bit 3 **BRG16:** 16-Bit Baud Rate Register Enable bit
1 = 16-bit Baud Rate Generator – SPBRGH and SPBRG
0 = 8-bit Baud Rate Generator – SPBRG only (Compatible mode), SPBRGH value ignored

bit 2 **Unimplemented:** Read as '0'

bit 1 **WUE:** Wake-up Enable bit
Asynchronous mode:
1 = EUSART will continue to sample the RX pin – interrupt generated on falling edge; bit cleared in hardware on following rising edge
0 = RX pin not monitored or rising edge detected
Synchronous mode:
Unused in this mode.

bit 0 **ABDEN**: Auto-Baud Detect Enable bit
Asynchronous mode:
1 = Enable baud rate measurement on the next character. Requires reception of a Sync field (55h); cleared in hardware upon completion.
0 = Baud rate measurement disabled or completed
Synchronous mode:
Unused in this mode.

## 19.2 EUSART Asynchronous Mode

The Asynchronous mode of operation is selected by clearing the SYNC bit (TXSTA<4>). In this mode, the EUSART uses standard Non-Return-to-Zero (NRZ) format (one Start bit, eight or nine data bits and one Stop bit). The most common data format is 8 bits. An on-chip dedicated 8-bit/16-bit Baud Rate Generator can be used to derive standard baud rate frequencies from the oscillator.

The EUSART transmits and receives the LSb first. The EUSART's transmitter and receiver are functionally independent but use the same data format and baud rate. The Baud Rate Generator produces a clock, either x16 or x64 of the bit shift rate depending on the BRGH and BRG16 bits (TXSTA<2> and BAUDCON<3>). Parity is not supported by the hardware, but can be implemented in software and stored as the 9th data bit.

When operating in Asynchronous mode, the EUSART module consists of the following important elements:

In Asynchronous mode, clock polarity is selected with the TXCKP bit (BAUDCON<4>). Setting TXCKP sets the Idle state on CK as high, while clearing the bit sets the Idle state as low. Data polarity is selected with the RXDTP bit (BAUDCON<5>).

Setting RXDTP inverts data on RX, while clearing the bit has no affect on received data.

- Baud Rate Generator
- Sampling Circuit
- Asynchronous Transmitter
- Asynchronous Receiver
- Auto-Wake-up on Sync Break Character
- 12-Bit Break Character Transmit
- Auto-Baud Rate Detection

### 19.2.1 EUSART ASYNCHRONOUS TRANSMITTER

The EUSART transmitter block diagram is shown in Figure 19-3. The heart of the transmitter is the Transmit (Serial) Shift Register (TSR). The Shift register obtains its data from the Read/Write Transmit Buffer register, TXREG. The TXREG register is loaded with data in software. The TSR register is not loaded until the Stop bit has been transmitted from the previous load. As soon as the Stop bit is transmitted, the TSR is loaded with new data from the TXREG register (if available).

Once the TXREG register transfers the data to the TSR register (occurs in one TCY), the TXREG register is empty and the TXIF flag bit (PIR1<4>) is set. This interrupt can be enabled or disabled by setting or clearing the interrupt enable bit, TXIE (PIE1<4>). TXIF will be set regardless of the state of TXIE; it cannot be cleared in software. TXIF is also not cleared immediately upon loading TXREG, but becomes valid in the second instruction cycle following the load instruction. Polling TXIF immediately following a load of TXREG will return invalid results.

While TXIF indicates the status of the TXREG register, another bit, TRMT (TXSTA<1>), shows the status of the TSR register. TRMT is a read-only bit which is set when the TSR register is empty. No interrupt logic is tied to this bit so the user has to poll this bit in order to determine if the TSR register is empty.

**Note 1:** The TSR register is not mapped in data memory so it is not available to the user.

**2:** Flag bit, TXIF, is set when enable bit, TXEN, is set.

To set up an Asynchronous Transmission:

1. Initialize the SPBRGH:SPBRG registers for the appropriate baud rate. Set or clear the BRGH and BRG16 bits, as required, to achieve the desired baud rate.
2. Enable the asynchronous serial port by clearing bit, SYNC, and setting bit, SPEN.
3. If interrupts are desired, set enable bit, TXIE.
4. If 9-bit transmission is desired, set transmit bit, TX9. Can be used as address/data bit.
5. Enable the transmission by setting bit, TXEN, which will also set bit, TXIF.
6. If 9-bit transmission is selected, the ninth bit should be loaded in bit, TX9D.
7. Load data to the TXREG register (starts transmission).
8. If using interrupts, ensure that the GIE and PEIE bits in the INTCON register (INTCON<7:6>) are set.

**NOTES:**

## 24.0 ECAN MODULE

PIC18F2480/2580/4480/4580 devices contain an Enhanced Controller Area Network (ECAN) module. The ECAN module is fully backward compatible with the CAN module available in PIC18CXX8 and PIC18FXX8 devices.

The Controller Area Network (CAN) module is a serial interface which is useful for communicating with other peripherals or microcontroller devices. This interface, or protocol, was designed to allow communications within noisy environments.

The ECAN module is a communication controller, implementing the CAN 2.0A or B protocol as defined in the BOSCH specification. The module will support CAN 1.2, CAN 2.0A, CAN 2.0B Passive and CAN 2.0B Active versions of the protocol. The module implementation is a full CAN system; however, the CAN specification is not covered within this data sheet. Refer to the BOSCH CAN specification for further details.

The module features are as follows:

- Implementation of the CAN protocol, CAN 1.2, CAN 2.0A and CAN 2.0B
- DeviceNet™ data bytes filter support
- Standard and extended data frames
- 0-8 bytes data length
- Programmable bit rate up to 1 Mbit/sec
- Fully backward compatible with the PIC18XXX8 CAN module
- Three modes of operation:
  - Mode 0 – Legacy mode
  - Mode 1 – Enhanced Legacy mode with DeviceNet support
  - Mode 2 – FIFO mode with DeviceNet support
- Support for remote frames with automated handling
- Double-buffered receiver with two prioritized received message storage buffers
- Six buffers programmable as RX and TX message buffers
- 16 full (standard/extended identifier) acceptance filters that can be linked to one of four masks
- Two full acceptance filter masks that can be assigned to any filter
- One full acceptance filter that can be used as either an acceptance filter or acceptance filter mask
- Three dedicated transmit buffers with application specified prioritization and abort capability
- Programmable wake-up functionality with integrated low-pass filter
- Programmable Loopback mode supports self-test operation
- Signaling via interrupt capabilities for all CAN receiver and transmitter error states
- Programmable clock source
- Programmable link to timer module for time-stamping and network synchronization
- Low-power Sleep mode

### 24.1 Module Overview

The CAN bus module consists of a protocol engine and message buffering and control. The CAN protocol engine automatically handles all functions for receiving and transmitting messages on the CAN bus. Messages are transmitted by first loading the appropriate data registers. Status and errors can be checked by reading the appropriate registers. Any message detected on the CAN bus is checked for errors and then matched against filters to see if it should be received and stored in one of the two receive registers.

The CAN module supports the following frame types:

- Standard Data Frame
- Extended Data Frame
- Remote Frame
- Error Frame
- Overload Frame Reception

The CAN module uses the RB2/CANTX and RB3/CANRX pins to interface with the CAN bus. In normal mode, the CAN module automatically overrides TRISB<2>. The user must ensure that TRISB<3> is set.

#### 24.1.1 MODULE FUNCTIONALITY

The CAN bus module consists of a protocol engine, message buffering and control (see Figure 24-1). The protocol engine can best be understood by defining the types of data frames to be transmitted and received by the module.

The following sequence illustrates the necessary initialization steps before the ECAN module can be used to transmit or receive a message. Steps can be added or removed depending on the requirements of the application.

1. Initial LAT and TRIS bits for RX and TX CAN.
2. Ensure that the ECAN module is in Configuration mode.
3. Select ECAN Operational mode.
4. Set up the Baud Rate registers.
5. Set up the Filter and Mask registers.
6. Set the ECAN module to normal mode or any other mode required by the application logic.

**REGISTER 24-21: RXERRCNT: RECEIVE ERROR COUNT REGISTER**

| R-0 | R-0 | R-0 | R-0 | R-0 | R-0 | R-0 | R-0 |
|---|---|---|---|---|---|---|---|
| REC7 | REC6 | REC5 | REC4 | REC3 | REC2 | REC1 | REC0 |
| bit 7 | | | | | | | bit 0 |

| **Legend:** | | | |
|---|---|---|---|
| R = Readable bit | W = Writable bit | U = Unimplemented bit, read as '0' | |
| -n = Value at POR | '1' = Bit is set | '0' = Bit is cleared | x = Bit is unknown |

bit 7-0 **REC<7:0>:** Receive Error Counter bits

This register contains the receive error value as defined by the CAN specifications. When RXERRCNT > 127, the module will go into an error-passive state. RXERRCNT does not have the ability to put the module in "bus-off" state.

**EXAMPLE 24-5: READING A CAN MESSAGE**

```
; Need to read a pending message from RXB0 buffer.
; To receive any message, filter, mask and RXM1:RXM0 bits in RXB0CON registers must be
; programmed correctly.
;
; Make sure that there is a message pending in RXB0.
BTFSS   RXB0CON, RXFUL                ; Does RXB0 contain a message?
BRA     NoMessage                     ; No. Handle this situation...
; We have verified that a message is pending in RXB0 buffer.
; If this buffer can receive both Standard or Extended Identifier messages,
; identify type of message received.
BTFSS   RXB0SIDL, EXID                ; Is this Extended Identifier?
BRA     StandardMessage               ; No. This is Standard Identifier message.
                                      ; Yes. This is Extended Identifier message.
; Read all 29-bits of Extended Identifier message.
...
; Now read all data bytes
MOVFF   RXB0DO, MY_DATA_BYTE1
...
; Once entire message is read, mark the RXB0 that it is read and no longer FULL.
BCF     RXB0CON, RXFUL                ; This will allow CAN Module to load new messages
                                      ; into this buffer.
...
```

#### 24.15.6.1 Receiver Overflow

An overflow condition occurs when the MAB has assembled a valid received message (the message meets the criteria of the acceptance filters) and the receive buffer associated with the filter is not available for loading of a new message. The associated RXBnOVFL bit in the COMSTAT register will be set to indicate the overflow condition. This bit must be cleared by the MCU.

#### 24.15.6.2 Receiver Warning

The receive error counter has reached the MCU warning limit of 96.

#### 24.15.6.3 Transmitter Warning

The transmit error counter has reached the MCU warning limit of 96.

#### 24.15.6.4 Receiver Bus Passive

This will occur when the device has gone to the error-passive state because the receive error counter is greater or equal to 128.

#### 24.15.6.5 Transmitter Bus Passive

This will occur when the device has gone to the error-passive state because the transmit error counter is greater or equal to 128.

#### 24.15.6.6 Bus-Off

The transmit error counter has exceeded 255 and the device has gone to bus-off state.

## GOTO — Unconditional Branch

Syntax: GOTO k

Operands: $0 \le k \le 1048575$

Operation: $k \rightarrow PC<20:1>$

Status Affected: None

Encoding:

| | | | | |
|---|---|---|---|---|
| 1st word (k<7:0>) | 1110 | 1111 | $k_7$kkk | kkk$k_0$ |
| 2nd word(k<19:8>) | 1111 | $k_{19}$kkk | kkkk | kkk$k_8$ |

Description: GOTO allows an unconditional branch anywhere within entire 2-Mbyte memory range. The 20-bit value 'k' is loaded into PC<20:1>. GOTO is always a two-cycle instruction.

Words: 2

Cycles: 2

Q Cycle Activity:

| Q1 | Q2 | Q3 | Q4 |
|---|---|---|---|
| Decode | Read literal 'k'<7:0>, | No operation | Read literal 'k'<19:8>, Write to PC |
| No operation | No operation | No operation | No operation |

Example: GOTO THERE

After Instruction
PC = Address (THERE)

## INCF — Increment f

Syntax: INCF f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: $(f) + 1 \rightarrow dest$

Status Affected: C, DC, N, OV, Z

Encoding:

| 0010 | 10da | ffff | ffff |
|---|---|---|---|

Description: The contents of register 'f' are incremented. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f'.

If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.

If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 26.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

| Q1 | Q2 | Q3 | Q4 |
|---|---|---|---|
| Decode | Read register 'f' | Process Data | Write to destination |

Example: INCF CNT, 1, 0

Before Instruction
CNT = FFh
Z = 0
C = ?
DC = ?
After Instruction
CNT = 00h
Z = 1
C = 1
DC = 1

**IORLW** **Inclusive OR Literal with W**

Syntax: IORLW k

Operands: $0 \le k \le 255$

Operation: (W) .OR. k → W

Status Affected: N, Z

Encoding:

| 0000 | 1001 | kkkk | kkkk |
|---|---|---|---|

Description: The contents of W are ORed with the eight-bit literal 'k'. The result is placed in W.

Words: 1

Cycles: 1

Q Cycle Activity:

| Q1 | Q2 | Q3 | Q4 |
|---|---|---|---|
| Decode | Read literal 'k' | Process Data | Write to W |

Example: IORLW 35h

Before Instruction
W = 9Ah
After Instruction
W = BFh

**IORWF** **Inclusive OR W with f**

Syntax: IORWF f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (W) .OR. (f) → dest

Status Affected: N, Z

Encoding:

| 0001 | 00da | ffff | ffff |
|---|---|---|---|

Description: Inclusive OR W with register 'f'. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f'.

If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.

If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 26.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

| Q1 | Q2 | Q3 | Q4 |
|---|---|---|---|
| Decode | Read register 'f' | Process Data | Write to destination |

Example: IORWF RESULT, 0, 1

Before Instruction
RESULT = 13h
W = 91h
After Instruction
RESULT = 13h
W = 93h

**TBLRD Table Read**

Syntax: TBLRD ( *; *+; *-; +*)

Operands: None

Operation: if TBLRD *,
(Prog Mem (TBLPTR)) → TABLAT,
TBLPTR – No Change;
if TBLRD *+,
(Prog Mem (TBLPTR)) → TABLAT,
(TBLPTR) + 1 → TBLPTR;
if TBLRD *-,
(Prog Mem (TBLPTR)) → TABLAT,
(TBLPTR) – 1 → TBLPTR;
if TBLRD +*,
(TBLPTR) + 1 → TBLPTR,
(Prog Mem (TBLPTR)) → TABLAT;

Status Affected: None

Encoding:

| | | | |
|---|---|---|---|
| 0000 | 0000 | 0000 | 10nn<br>nn=0 *<br>=1 *+<br>=2 *–<br>=3 +* |

Description: This instruction is used to read the contents of Program Memory (P.M.). To address the program memory, a pointer, called Table Pointer (TBLPTR), is used.

The TBLPTR (a 21-bit pointer) points to each byte in the program memory. TBLPTR has a 2-Mbyte address range.

TBLPTR[0] = 0: Least Significant Byte of Program Memory Word
TBLPTR[0] = 1: Most Significant Byte of Program Memory Word

The TBLRD instruction can modify the value of TBLPTR as follows:

- no change
- post-increment
- post-decrement
- pre-increment

Words: 1

Cycles: 2

Q Cycle Activity:

| Q1 | Q2 | Q3 | Q4 |
|---|---|---|---|
| Decode | No operation | No operation | No operation |
| No operation | No operation (Read Program Memory) | No operation | No operation (Write TABLAT) |

**TBLRD Table Read (Continued)**

Example 1:
```
TBLRD  *+ ;
```
Before Instruction
TABLAT = 55h
TBLPTR = 00A356h
MEMORY(00A356h) = 34h
After Instruction
TABLAT = 34h
TBLPTR = 00A357h

Example 2:
```
TBLRD  +* ;
```
Before Instruction
TABLAT = 0AAh
TBLPTR = 01A357h
MEMORY(01A357h) = 12h
MEMORY(01A358h) = 34h
After Instruction
TABLAT = 34h
TBLPTR = 01A358h

## 28.2 DC Characteristics: Power-Down and Supply Current PIC18F2480/2580/4480/4580 (Industrial, Extended) PIC18LF2480/2580/4480/4580 (Industrial) (Continued)

| | | | | | | | |
|---|---|---|---|---|---|---|---|
| **PIC18LF2480/2580/4480/4580** (Industrial) | | **Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial | | | | | |
| **PIC18F2480/2580/4480/4580** (Industrial, Extended) | | **Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial<br>-40°C ≤ TA ≤ +125°C for extended | | | | | |
| **Param No.** | **Device** | **Typ** | **Max** | **Units** | **Conditions** | | |
| | **Supply Current (IDD)(2,3)** | | | | | | |
| | PIC18LF2X80/4X80 | 19 | 31 | µA | -40°C | VDD = 2.0V | FOSC = 31 kHz (**RC_RUN** mode, Internal oscillator source) |
| | | 21 | 31 | µA | +25°C | | |
| | | 22 | 31 | µA | +85°C | | |
| | PIC18LF2X80/4X80 | 57 | 60 | µA | -40°C | VDD = 3.0V | |
| | | 47 | 60 | µA | +25°C | | |
| | | 42 | 60 | µA | +85°C | | |
| | All devices | 150 | 170 | µA | -40°C | VDD = 5.0V | |
| | | 113 | 170 | µA | +25°C | | |
| | | 98 | 170 | µA | +85°C | | |
| | Extended devices only | 170 | 280 | µA | +125°C | | |
| | PIC18LF2X80/4X80 | 530 | 1030 | µA | -40°C | VDD = 2.0V | FOSC = 1 MHz (**RC_RUN** mode, Internal oscillator source) |
| | | 550 | 1030 | µA | +25°C | | |
| | | 560 | 1030 | µA | +85°C | | |
| | PIC18LF2X80/4X80 | 940 | 1150 | µA | -40°C | VDD = 3.0V | |
| | | 900 | 1150 | µA | +25°C | | |
| | | 880.0 | 1150 | µA | +85°C | | |
| | All devices | 1.8 | 2.3 | mA | -40°C | VDD = 5.0V | |
| | | 1.7 | 2.3 | mA | +25°C | | |
| | | 1.7 | 2.3 | mA | +85°C | | |
| | Extended devices only | 2.6 | 3.6 | mA | +125°C | | |

**Legend:** Shading of rows is to assist in readability of the table.

**Note 1:** The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

**2:** The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD;
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

**3:** For RC oscillator configurations, current through REXT is not included. The current through the resistor can be estimated by the formula, Ir = VDD/2REXT (mA), with REXT in kΩ.

**4:** Standard low-cost 32 kHz crystals have an operating temperature range of -10°C to +70°C. Extended temperature crystals are available at a much higher cost.

**TABLE 28-24: A/D CONVERTER CHARACTERISTICS: PIC18F2480/2580/4480/4580 (INDUSTRIAL) PIC18LF2480/2580/4480/4580 (INDUSTRIAL)**

| Param No. | Sym | Characteristic | | Min | Typ | Max | Units | Conditions |
|---|---|---|---|---|---|---|---|---|
| A01 | NR | Resolution | | — | — | 10 | bit | ΔVREF ≥ 3.0V |
| A03 | EIL | Integral Linearity Error | | — | — | <±1 | LSb | ΔVREF ≥ 3.0V |
| A04 | EDL | Differential Linearity Error | | — | — | <±1 | LSb | ΔVREF ≥ 3.0V |
| A06 | EOFF | Offset Error | | — | — | <±2 | LSb | ΔVREF ≥ 3.0V |
| A07 | EGN | Gain Error | | — | — | <±1 | LSb | ΔVREF ≥ 3.0V |
| A10 | — | Monotonicity | | Guaranteed(1) | | | — | |
| A20 | ΔVREF | Reference Voltage Range (VREFH – VREFL) | | 3 | — | AVDD – AVSS | V | For 10-bit resolution |
| A21 | VREFH | Reference Voltage High | | AVSS + 3.0V | — | AVDD + 0.3V | V | For 10-bit resolution |
| A22 | VREFL | Reference Voltage Low | | AVSS – 0.3V | — | AVDD – 3.0V | V | For 10-bit resolution |
| A25 | VAIN | Analog Input Voltage | | VREFL | — | VREFH | V | |
| A28 | AVDD | Analog Supply Voltage | | VDD – 0.3 | — | VDD + 0.3 | V | |
| A29 | AVSS | Analog Supply Voltage | | VSS – 0.3 | — | VSS + 0.3 | V | |
| A30 | ZAIN | Recommended Impedance of Analog Voltage Source | | — | — | 2.5 | kΩ | |
| A40 | IAD | A/D Conversion Current (VDD) | PIC18**F**XXXX | — | 180 | — | μA | Average current consumption when A/D is on **(Note 2)** |
| | | | PIC18**LF**XXXX | — | 90 | — | μA | VDD = 2.0V; average current consumption when A/D is on **(Note 2)** |
| A50 | IREF | VREF Input Current **(Note 3)** | | —<br>— | —<br>— | ±5<br>±150 | μA<br>μA | During VAIN acquisition.<br>During A/D conversion cycle. |

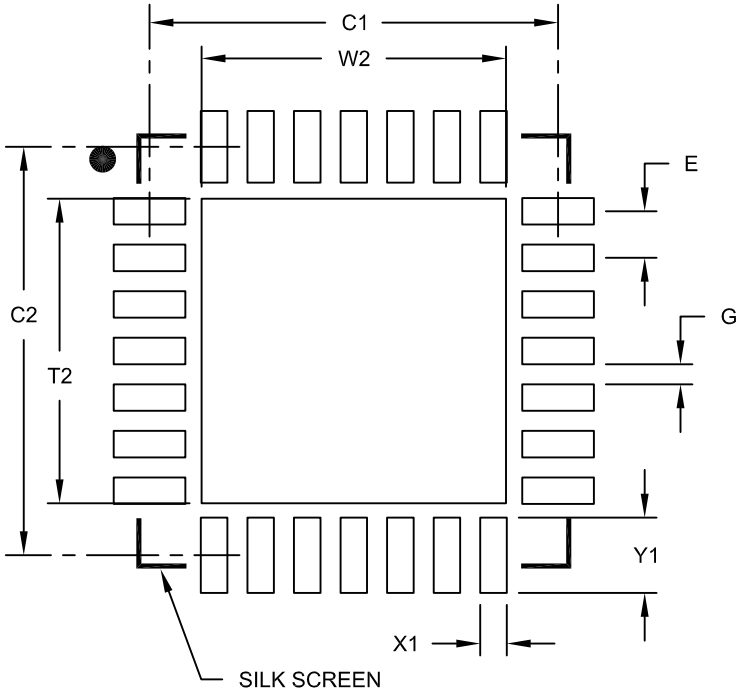
**Note 1:** The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.

**2:** When A/D is off, it will not consume any current other than minor leakage current. The power-down current spec includes any such leakage from the A/D module.

**3:** VREFH current is from RA3/AN3/VREF+ pin or AVDD, whichever is selected as the VREFH source. VREFL current is from RA2/AN2/VREF- pin or AVSS, whichever is selected as the VREFL source.

### 28-Lead Plastic Quad Flat, No Lead Package (ML) – 6x6 mm Body [QFN] with 0.55 mm Contact Length

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging




RECOMMENDED LAND PATTERN

| Units | | MILLIMETERS | | |
|---|---|---|---|---|
| Dimension Limits | | MIN | NOM | MAX |
| Contact Pitch | E | | 0.65 BSC | |
| Optional Center Pad Width | W2 | | | 4.25 |
| Optional Center Pad Length | T2 | | | 4.25 |
| Contact Pad Spacing | C1 | | 5.70 | |
| Contact Pad Spacing | C2 | | 5.70 | |
| Contact Pad Width (X28) | X1 | | | 0.37 |
| Contact Pad Length (X28) | Y1 | | | 1.00 |
| Distance Between Pads | G | 0.20 | | |

Notes:

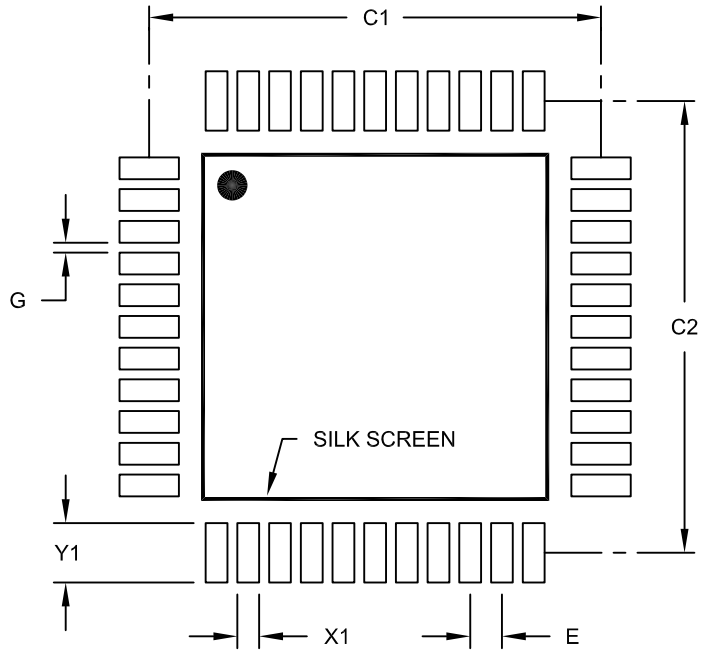
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2105A

### 44-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging




RECOMMENDED LAND PATTERN

| Units | | MILLIMETERS | | |
|---|---|---|---|---|
| Dimension Limits | | MIN | NOM | MAX |
| Contact Pitch | E | | 0.80 BSC | |
| Contact Pad Spacing | C1 | | 11.40 | |
| Contact Pad Spacing | C2 | | 11.40 | |
| Contact Pad Width (X44) | X1 | | | 0.55 |
| Contact Pad Length (X44) | Y1 | | | 1.50 |
| Distance Between Pads | G | 0.25 | | |

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2076A